



ASMGEN.003APC

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

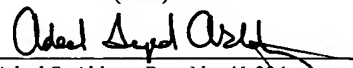
Applicant : Park et al.
Appl. No. : 10/500,494
Filed : December 28, 2002
For : METHOD OF FORMING
COPPER INTERCONNECTIONS
FOR SEMICONDUCTOR
INTEGRATED CIRCUITS ON A
SUBSTRATE
Examiner : Thanh V. Pham
Group Art Unit : 2823

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

August 10, 2005

(Date)


Adeel S. Akhtar, Reg. No. 41,394

PRELIMINARY AMENDMENT

Mail Stop Amendment

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Prior to examination on the merits in the above-referenced application, please amend the application as indicated below.

Amendments to the Specification begin on page 2 of this paper.

Remarks/Arguments begin on page 3 of this paper.